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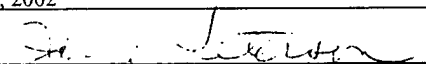
PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Shinji Isokawa Examiner: Wai Sing Louie  
Serial No.: 09/731,889 ✓ Group Art Unit: 2814  
Confirmation No.: 1026 Docket No.: 362-51  
Filed: December 7, 2000 ✓ Dated: May 3, 2002  
For: CHIP-TYPE SEMICONDUCTOR ✓  
LIGHT-EMITTING DEVICE

Commissioner for Patents  
Washington, DC 20231

*I hereby certify this correspondence is being deposited with the  
United States Postal Service as first class mail, postpaid in an  
envelope, addressed to: Commissioner for Patents, Washington,  
D.C. 20231  
On May 3, 2002*

Signature: **REPLY TO NON-FINAL OFFICE ACTION**

Sir:

In response to the non-final Office Action mailed February 7, 2002, a reply to which  
is due May 7, 2002, please amend the above-identified application as follows:

**IN THE SPECIFICATION:**

At page 4, replace the paragraph beginning at line 18 with the following:

31 Furthermore, a translucent-synthetic-resin mold 24 is formed on the upper surface of  
the substrate 12. The mold encapsulates the protrusion 14b, protrusion 16b, pad 16c, LED  
chip 20 and metal wire 22.

**IN THE CLAIMS:**

Please amend Claims 1 and 2 by rewriting the same as follows:

1. (Amended) A chip-type semiconductor light-emitting device, comprising:  
a pair of electrodes, at least one of said pair of electrodes including an inner portion  
and an outer portion;

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